

SURFACE MOUNT RECTIFIER

REVERSE VOLTAGE: 50 - 1000 V
CURRENT: 1.0 A

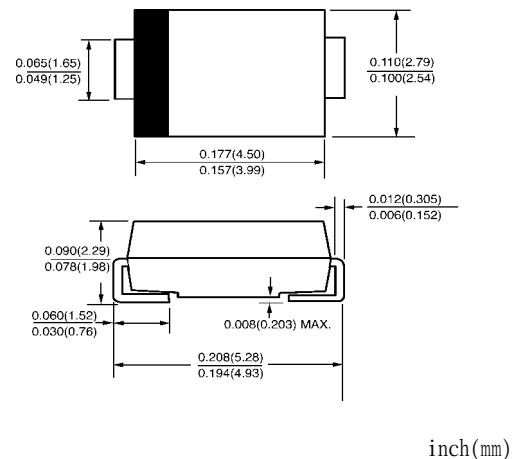
FEATURES

- ◇ Plastic package has underwriters laboratory flammability classifications
- ◇ For surface mounted applications
- ◇ Low profile package
- ◇ Built-in strain relief, ideal for automated placement
- ◇ Glass passivated chip junction
- ◇ High temperature soldering:
250°C/10 seconds at terminals

MECHANICAL DATA

- ◇ Case: JEDEC DO-214AC, molded plastic over passivated chip
- ◇ Terminals: Solder Plated, solderable per MIL-STD-750, Method 2026
- ◇ Polarity: Color band denotes cathode end
- ◇ Weight: 0.002 ounces, 0.064 gram

DO - 214AC(SMA)



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified

		S1A	S1B	S1D	S1G	S1J	S1K	S1M	UNITS
Device marking code		SA	SB	SD	SG	SJ	SK	SM	
Maximum recurrent peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current @T _L =110°C	I _{F(AV)}	1.0							A
Peak forward surge current @ T _L = 110°C 8.3ms single half-sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	40.0					30.0		A
Maximum instantaneous forward voltage at 1.0A	V _F	1.1							V
Maximum DC reverse current @T _A =25°C at rated DC blocking voltage @T _A =125°C	I _R	5.0 50.0							μ A
Typical junction capacitance(NOTE 1)	C _J	15							pF
Typical thermal resistance (NOTE 2)	R _{θJA}	50							°C/W
Operating junction and storage temperature range	T _J T _{STG}	-55-----+175							°C

NOTE: 1.Measured at 1.0MHz and applied reverse voltage of 4.0volts

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2.Thermal resistance from junction to ambient and junction to lead P.C.B mounted on 0.27"X0.27"(7.0X7.0mm2) copper pad areas.

FIG.1 – FORWARD DERATING CURVE

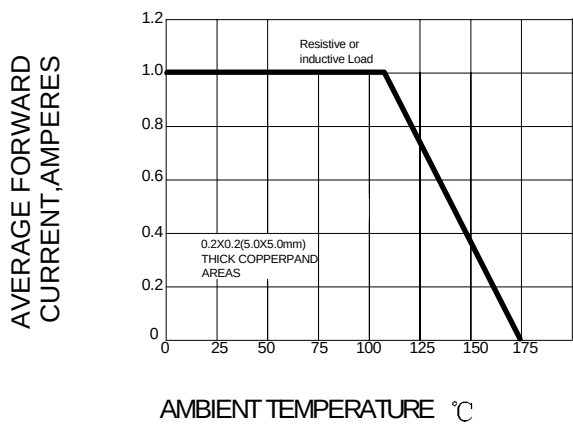


FIG.2 PEAK FORWARD SURGE CURRENT

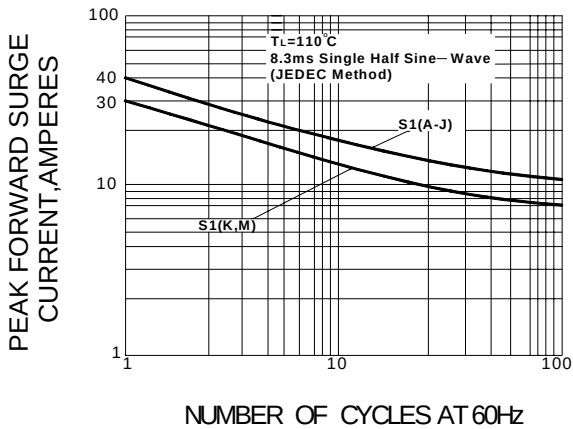


FIG.3 – TYPICAL FORWARD CHARACTERISTICS

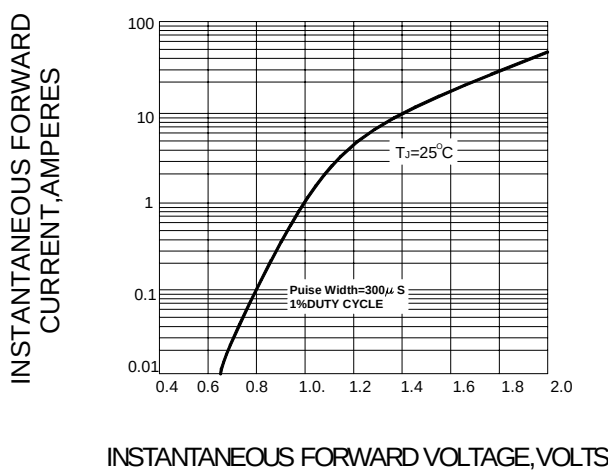


FIG.4 – TYPICAL REVERSE CHARACTERISTICS

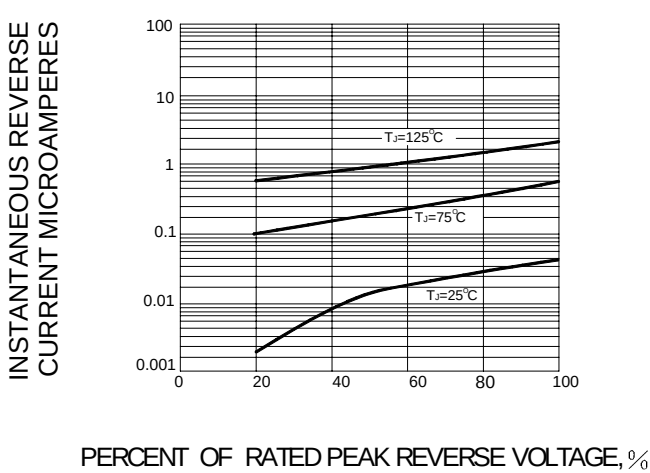


FIG.5-TYPICAL JUNCTION CAPACITANCE

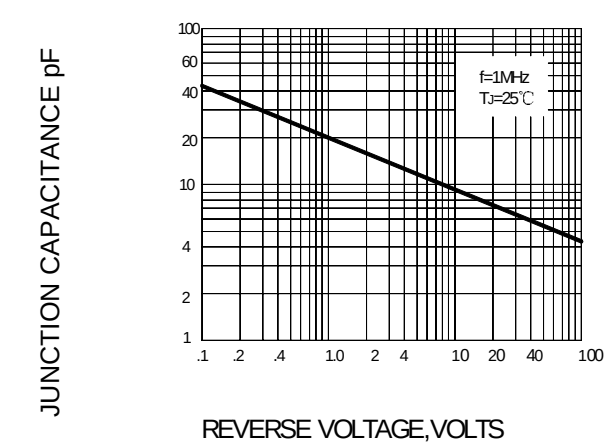


FIG.6-TRANSIENT THERMAL IMPEDANCE

